



160.000<sup>+ .000</sup>  
- .012

219.964<sup>+ .000</sup>  
- .012

Notes:

1. Some parts will not be installed, see BOM file.
2. Dimensions in mm.
3. No Centroid data provided. Assembly house shall generate it from Gerber Files if needed.

<small>UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES ARE: FRACTIONS DECIMALS ANGLES - .010 - .005 - .002 DO NOT SCALE DRAWING</small>	CONTRACT NO.		UNIVERSITY OF CHICAGO ELECTRONICS DEVELOPMENT GROUP	
	APPROVALS	DATE	TITLE	
	DRAWN M. Bogdan	8/16/10	PSEC2 Flip Chip ADC Module Assembly drawing - Top	
	CHECKED M. Bogdan	8/16/10	SIZE C	DWG. NO. 2709 Top
ISSUED		SCALE	REV. A	
SIMILAR TO	ACT. M	CALC. M	SHEET 1 of 1	